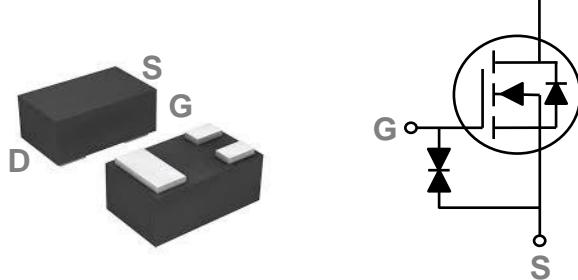


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT883 Pin Configuration



BVDSS	RDSON	ID
60V	3Ω	200mA

### Features

- 60V,200mA, RDS(ON) =3Ω@VGS = 10V
- Worldwide Smallest Package : 1x0.6x0.45 mm
- Fast switching
- Green Device Available
- 2KV HBM ESD Capability

### Applications

- Notebook
- Smartphone
- Battery Protection
- Hand-held Instruments

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	200	mA
	Drain Current – Continuous ( $T_A=70^\circ\text{C}$ )	160	mA
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	800	mA
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	156	mW
	Power Dissipation – Derate above 25°C	1.25	mW/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	800	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	uA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 20$	uA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=0.15\text{A}$	---	1.4	3	$\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=0.1\text{A}$	---	1.6	4	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = 250\mu\text{A}$	1.2	2	2.5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=0.1\text{A}$	---	0.3	---	S

**Dynamic and switching Characteristics**

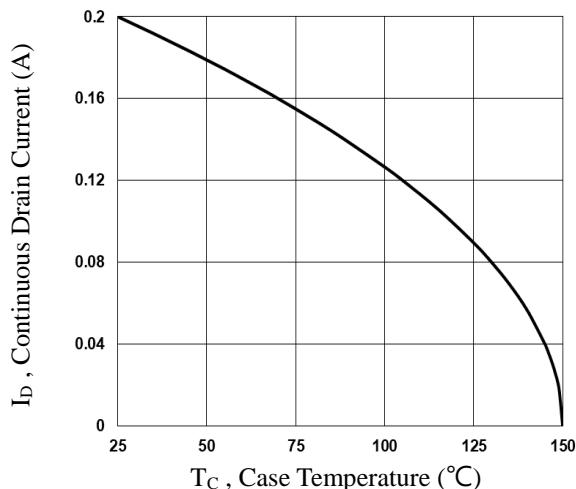
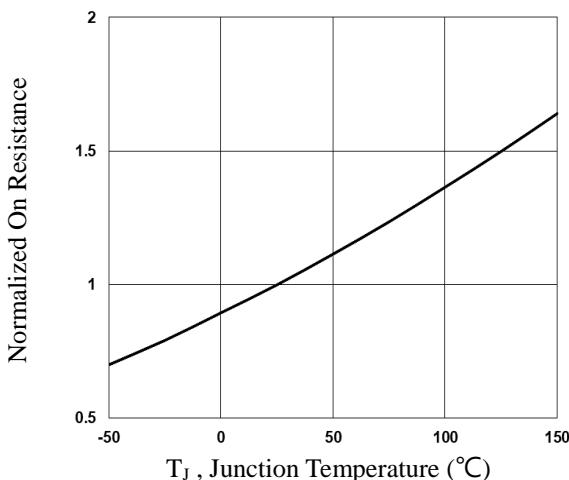
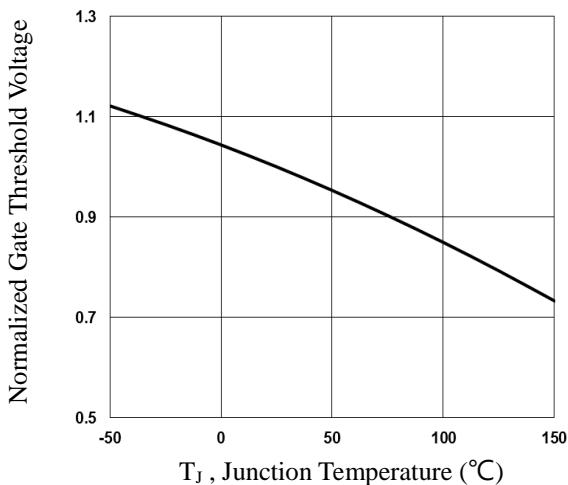
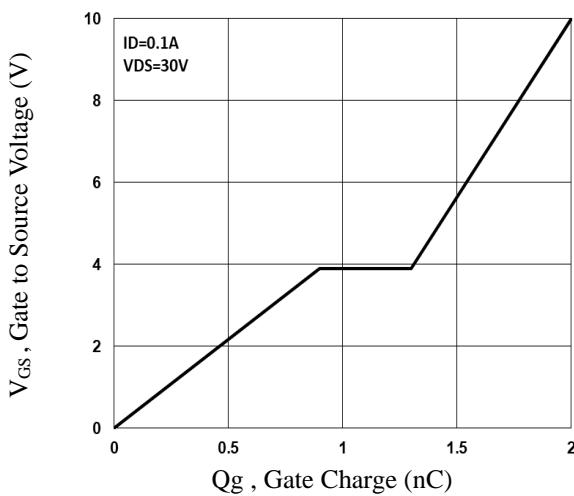
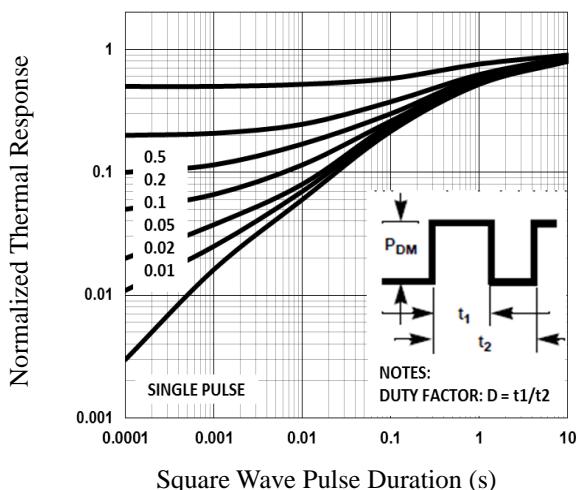
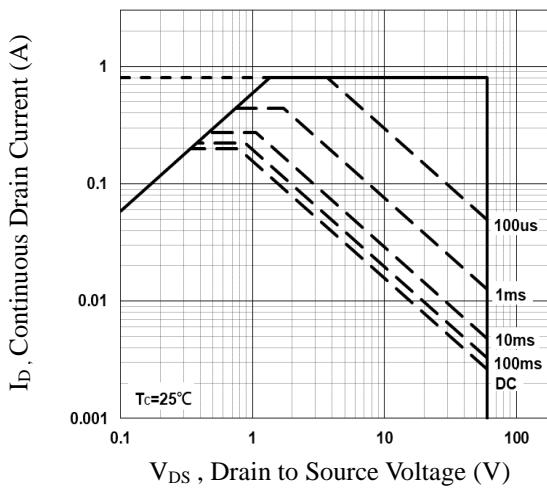
$Q_g$	Total Gate Charge <sup>2, 3</sup>	$V_{DS}=30\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=0.1\text{A}$	---	2	3	nC
$Q_{gs}$	Gate-Source Charge <sup>2, 3</sup>		---	0.9	1.4	
$Q_{gd}$	Gate-Drain Charge <sup>2, 3</sup>		---	0.4	0.6	
$T_{d(on)}$	Turn-On Delay Time <sup>2, 3</sup>	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=6\Omega$ $I_D=0.1\text{A}$	---	3	6	ns
$T_r$	Rise Time <sup>2, 3</sup>		---	5	10	
$T_{d(off)}$	Turn-Off Delay Time <sup>2, 3</sup>		---	14	27	
$T_f$	Fall Time <sup>2, 3</sup>		---	9	17	
$C_{iss}$	Input Capacitance	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	25	38	pF
$C_{oss}$	Output Capacitance		---	15	23	
$C_{rss}$	Reverse Transfer Capacitance		---	6.8	10	

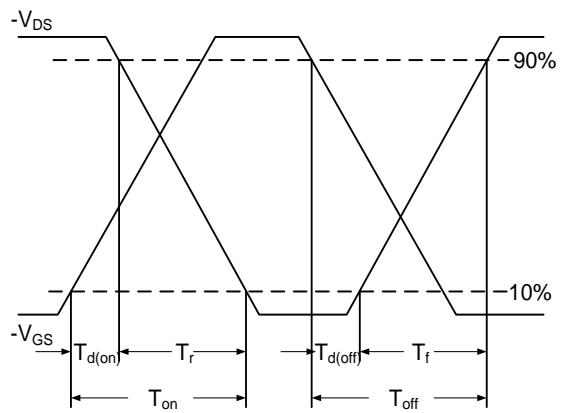
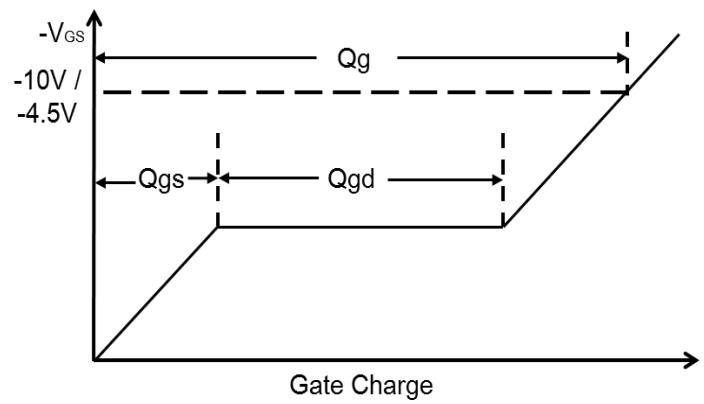
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	200	mA
			---	---	400	mA
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=0.1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
$T_{rr}$	Reverse Recovery Time	$V_R=50\text{V}$ , $I_s=0.1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	18	ns	
$Q_{rr}$	Reverse Recovery Charge		---	6	ns	nC

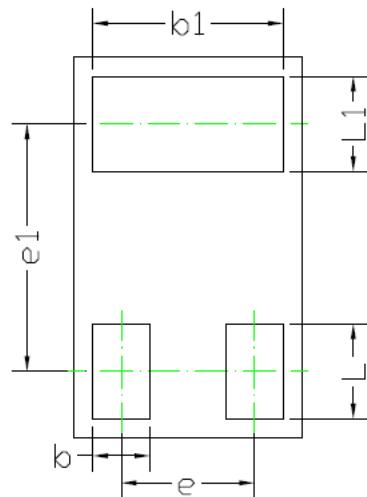
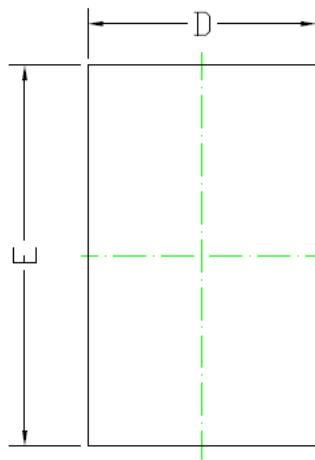
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

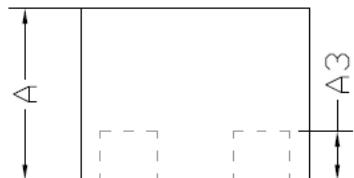

**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

## SOT883 PACKAGE INFORMATION



SIDE VIEW



SYMBOL	COMMON		
	DIMENSIONS MILLIMETER		
	MIN	NOM.	MAX
A	0.40	0.45	0.50
A3	0.127 BSC		
D	0.55	0.60	0.65
E	0.95	1.00	1.05
e	0.35 BSC		
e1	0.65 BSC		
b	0.13	0.15	0.18
b1	0.45	0.50	0.55
L	0.20	0.25	0.30
L1	0.20	0.25	0.30